

Electronic Acknowledgement Receipt

EFS ID:	10398681
Application Number:	10755042
International Application Number:	
Confirmation Number:	8665
Title of Invention:	Integrated chip package structure using silicon substrate and method of manufacturing the same
First Named Inventor/Applicant Name:	Mou-Shiung Lin
Customer Number:	89518
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Filer Authorized By:	Dennis Alan Duchene
Attorney Docket Number:	085027-0104
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Time Stamp:	21:59:54
Application Type:	Utility under 35 USC 111(a)

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Submitted with Payment	yes
Payment Type	Deposit Account
Payment was successfully received in RAM	\$810
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/Message Digest	Multi Part/.zip	Pages (if appl.)
1	Transmittal Letter	Transmittal.pdf	66241 199ab923437be0bd30a977dd061325e68 cc45d	no	1

Warnings:

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2	Request for Continued Examination (RCE)	RCE.pdf	93957 0e135c0146c1e125a8fb-1fcfd13a4110c40 a608	no	1
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Information:

3		ResponsetoFinalOA.pdf	122627 c099c7f1_a285172aef1ba42a5a-296c935cf5 28fa	yes	14
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Multipart Description/PDF files in .zip description

Document Description	Start	End
Amendment After Final	1	1
Claims	2	8
Applicant Arguments/Remarks Made in an Amendment	9	14

Warnings:

Information:

4	Miscellaneous Incoming Letter	Appendix.pdf	48189 221bb89de601147568f8a30915e13af9051 c509	no	1
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Information:

5	Transmittal Letter	IDS-Transmittal.pdf	65153 61b03d140e024493c995ea99c0dec80579c 568da	no	2
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Information:

6	Information Disclosure Statement (IDS) Form (SB08)	IDS-1449.pdf	85022 7ed57d5ebf1406e9ab360507a1774fe90a 636087	no	1
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7	Transmittal Letter	MG-0104-062711-IDS-Transmittal.pdf	65620 6aa3fd58e7fc5f4ea05975ef2afD1422c2d189	no	2
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8	Information Disclosure Statement (IDS) Form (SB06)	MG-0104-062711-IDS-1449.pdf	106445 3972ecfa121bb6fa2fe5cad9c9918796d1e1d423	no	3
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9	Non Patent Literature	ELECTRONIC_MATERIALS_HANDBOOK_VOL_1.pdf	811945 93ae654b6fb3c01e141b10fe2476fa1e9ffca350b7	no	10
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Warnings:**Information:**

10	Non Patent Literature	KUO_Semiconductor_Packaging_Engineering.pdf	448133 e2dd4ddce0dd8fb99775bf0d647e395add4c2c90	no	3
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Warnings:**Information:**

11	Fee Worksheet (SB06)	fee-info.pdf	29976 e8d16508fb3418fe3e734176aa064537f6d055x3	no	2
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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

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